

485 Series Fuse









Agency Approvals Ampere Rating Agency **Agency File Number** W E10480 1A - 3.15A **(12)** 29862 1A - 3.15A

Electrical Characteristics for Series

	% of Ampere Rating	Opening Time at 25°C
ĺ	100%	4 hours, Minimum
	200%	60 seconds, Maximum

Description

The 485 Nano^{2®} Fuse Series is a small, fast-acting, surface mount ceramic fuse rated at a remarkable 600VDC at its small size and with 100A breaking capacity. It is primarily designed for circuit protection in high energy applications. This product is fully compatible with lead-free solder alloys and higher temperature profiles associated with lead-free assembly.

Features

- Fast-Acting / Surface mount high fuse for voltage (up to 600VDC) applications.
- Fully compatible with lead-free solder alloys and higher temperature profiles associated with lead-free assembly.
- Relatively high breaking capacity at 100A.
- RoHS compliant / Halogen Free
- Rating 1 3.15 Amperes.

Applications

- PC server and Telecom systems
- LCDTV inverter boards DC input protection
- Uninterruptible Power Supply (UPS) / 3-Phase Power Supplies
- 380VDC server / lighting in data center

Additional Information







Samples

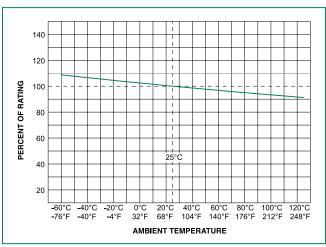
Electrical Specifications by Item

Amnere	Ampere Rating Amp Code (A)	Max Voltage Rating Inter (V)		Nominal Cold Resistance (Ohms)	Nominal Melting l²t (A²sec)	Agency Approvals	
Rating			Interrupting Rating			27 °	© .
1.00	001.	600	100A@600VDC, 100A@250VAC	0.264	0.3044	X	X
1.50	01.5	600		0.123	0.3917	X	X
2.00	002.	600		0.0744	0.8962	X	X
2.50	02.5	600		0.0583	1.4921	X	X
3.15	3.15	600		0.0395	3.304	X	X

- 1. Cold resistance measured at less than 10% of rated current at 23°C.
- 2. Agency Approval Table Key: X=Approved or Certified, P=Pending and Blank=Not Approved.
- 3. I2t values stated for 8 msec opening time.



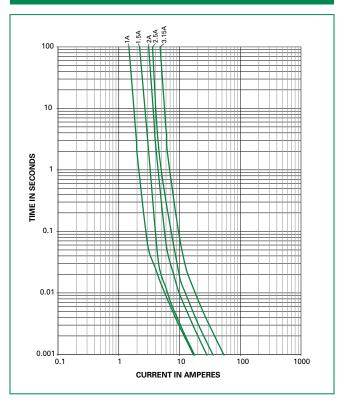
Temperature Re-rating Curve



Note:

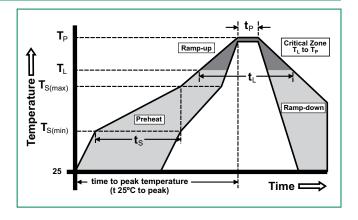
 Rerating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Average Time Current Curves



Soldering Parameters - Reflow Soldering

Reflow Co	ndition	Pb – Free Assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (Min to Max) (t _s)	60 – 180 ses	
Average R (T _L) to pea	amp-up Rate (Liquidus Temp k)	5°C/second max.	
T _{S(max)} to T _l	- Ramp-up Rate	5°C/second max.	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
	-Temperature (t _L)	60 – 150 seconds	
PeakTemperature (T _P)		260+0/-5 °C	
Time with Temperatu	in 5°C of actual peak ure (t _p)	20 - 40 seconds	
Ramp-dov	vn Rate	5°C/second max.	
Time 25°C	to peakTemperature (T _P)	8 minutes max.	
Do not exceed		260°C	





Product Characteristics

Material	Body: Ceramic Cap: Silver Plated Brass	
Product Marking	Body: Brand Logo, Current Rating	
Operating Temperature	-55°C to 125°C with proper derating	
Moisture Sensitivity Level	Level 1 J-STD-020	
Solderability	MIL-STD-202, Method 208	
Insulation Resistance (after Opening)	MIL-STD-202, Method 302, Test Condition A (10,000 ohms, Minimum)	

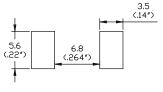
Thermal Shock	MIL-STD-202, Method 107, Test Condition B, 5 cycles, -65°C to 125 15 minutes @ each extreme		
Mechanical Shock	MIL-STD-202, Method 213, Test Condition I: Deenergized. 100G's peak amplitude, sawtooth wave 6ms duration, 3 cycles XYZ+xyz = 18 shocks		
Vibratio	MIL-STD-202, Method 201: 0.03" amplitude, 10-55 Hz in 1 min. 2 hrs. each XYZ=6hrs		
Moisture Resistance	MIL-STD-202, Method 106, 10 cycles		
Salt Spray	MIL-STD-202, Method 101, Test Condition B (48hrs)		
Resistance to Soldering Heat MIL-STD-202, Method 210, Test Condition B (10 sec at 260°C)			

Dimensions

12.1 (.475°) 4.5 (.177°) E 3.15A F

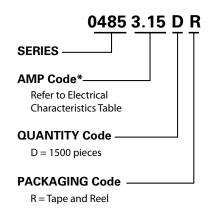
END CAP

Recommended Pad Layout



REFLOW SOLDER

Part Numbering System



*Example 3.15 amp is 04853.15DR

Packaging

Packaging Option	Packaging Specification	Quantity	Ouantity & Option Code	
24mm Tape and Reel	EIA-RS 481-1, (IEC 286, Part 3	1500	DR	